



Material Content Data Sheet



Sales Product Name	SAB-C161PI-LM CA			Issued		29. August 2013		
MA#	MA000733216							
Package	PG-MQFP-100-2			Weight*		1786.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	16.055	0.90	0.90	8985	8985
leadframe	non noble metal	magnesium	7439-95-4	0.538	0.03		301	
	inorganic material	silicon	7440-21-3	2.331	0.13		1304	
	non noble metal	nickel	7440-02-0	10.756	0.60		6019	
	non noble metal	copper	7440-50-8	344.917	19.30	20.06	193020	200644
wire	noble metal	gold	7440-57-5	3.785	0.21	0.21	2118	2118
encapsulation	organic material	carbon black	1333-86-4	6.917	0.39		3871	
	plastics	epoxy resin	-	200.582	11.22		112248	
	inorganic material	silicondioxide	60676-86-0	1175.827	65.82	77.43	658006	774125
leadfinish	non noble metal	tin	7440-31-5	19.520	1.09	1.09	10924	10924
plating	noble metal	silver	7440-22-4	1.857	0.10	0.10	1039	1039
glue	plastics	epoxy resin	-	0.967	0.05		541	
	noble metal	silver	7440-22-4	2.901	0.16	0.21	1624	2165
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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